

IN THE CLAIMS

Please amend the claims as follows:

1. (original) A photolithographic process comprising the steps of:

- applying a photoresist layer (2), with a substantially uniform thickness, on a substrate (1),
- locally exposing the photoresist layer (2) to a radiation source with a suitable wavelength,
- providing a suitable liquid developer composition on the substrate (1),
- dissolving an exposed or unexposed region of the photoresist layer (2) with the developer composition,
- rinsing and drying the photoresist layer (2) thereby interrupting said dissolving step,

wherein the substrate (1) has a metallic surface (1c) in contact with the photoresist layer (2) and the photoresist layer (2) has a thickness $d_r < 100\text{nm}$.

2. (original) A photolithographic process as claimed in claim 1, wherein the substrate comprises a metallic surface layer (1b), with a thickness d_m larger than approximately 10nm, and a further substrate material (1a).

3. (currently amended) A photolithographic process as claimed in claim 1 or 2, wherein the metallic surface (1c) comprises the chemical elements Ni, Cr or Au.

4. (currently amended) A photolithographic process as claimed in any one of claims 1 to 3 claim 1, wherein the photoresist (2) is a positive novolac resin-based photoresist.

5. (currently amended) A photolithographic process as claimed in any one of claims 1 to 4 claim 1, wherein the substrate (1a, 1b) is a master substrate for the production of a high density optical medium.

6. (original) A stamper (3) for the production of optical data storage media, manufactured by using the master substrate as used in claim 5.

7. (original) Use of a stamper (3) as claimed in claim 6 for the manufacture of a high density optical data storage medium.

8. (original) An optical data storage medium produced in an injection molding process by using the stamper (3) of claim 6.